

Features

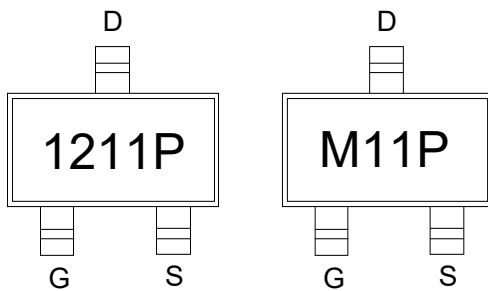
- Trench Power LV MOSFET technology
- High Density Cell Design for Low $R_{DS(ON)}$
- High Speed switching

Product Summary

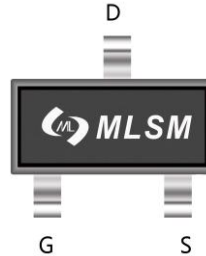
V_{DS}	$R_{DS(ON)}$ TYP	I_D
-12V	12m Ω @-4.5V	-11A
	17m Ω @-2.5V	

Application

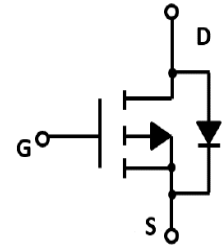
- Battery protection
- Load switch
- Power management



Marking and pin assignment



SOT-23 top view



Schematic diagram



Halogen-Free

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
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Common Ratings (TC=25°C Unless Otherwise Noted)

V_{DS}	Drain-Source Breakdown Voltage	-12	V
V_{GS}	Gate-Source Voltage	± 12	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
I_S	Diode Continuous Forward Current	$T_c=25^\circ\text{C}$ -11	A

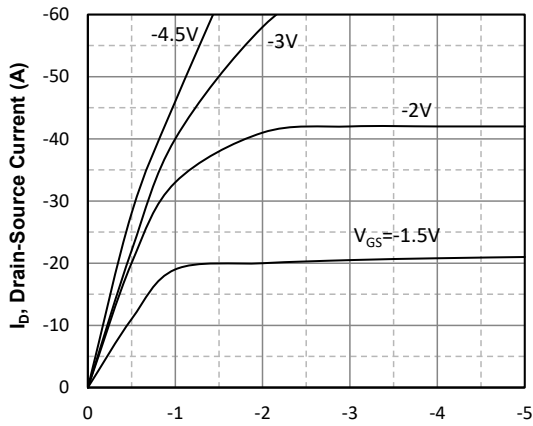
Mounted on Large Heat Sink

I_{DM}	Pulse Drain Current Tested	$T_c=25^\circ\text{C}$ -46	A
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$ -11	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$ 0.5	W
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient	270	°C/W

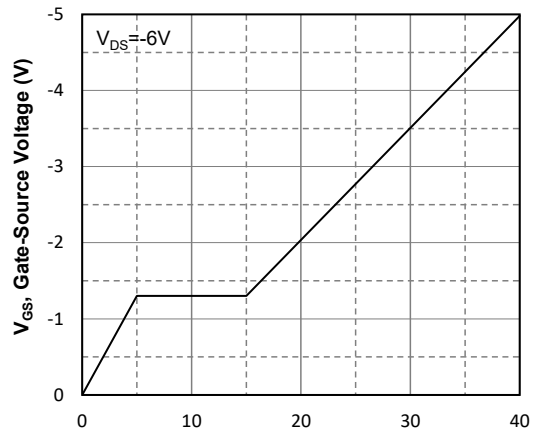
Ordering Information (Example)

Type	Package	Marking	Minimum Package(pcs)	Inner Box Quantity(pcs)	Outer Carton Quantity(pcs)	Delivery Mode
MLS1211P	SOT-23	1211P/M11P	3,000	45,000	180,000	7"reel

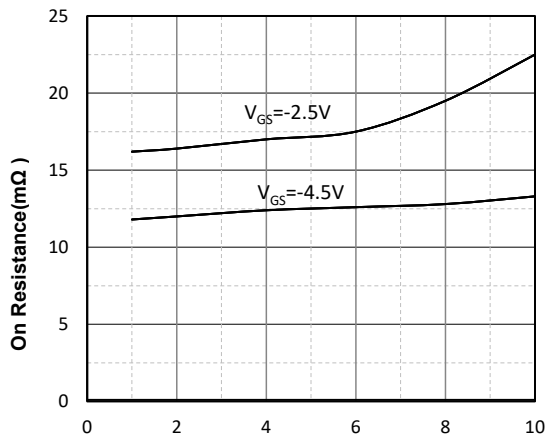
Electrical Characteristics (T _J =25°C unless otherwise noted)						
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
B _{V(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-12	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-12V, V _{GS} =0V	--	--	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.4	-0.7	-1.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-6.0A	--	12	17	mΩ
		V _{GS} =-2.5V, I _D =-6.0A	--	17	25	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{ISS}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1MHz	--	2700	--	pF
C _{OSS}	Output Capacitance		--	680	--	pF
C _{RSS}	Reverse Transfer Capacitance		--	590	--	pF
Switching Characteristics						
Q _g	Total Gate Charge	V _{DS} =-10V, I _D =-1A, V _{GS} =-10V	--	35	--	nC
Q _{gs}	Gate Source Charge		--	5	--	nC
Q _{gd}	Gate Drain Charge		--	10	--	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =-6V, I _D =-6A, V _{GS} =-4.5V, R _G =2.5Ω	--	11	--	nS
t _r	Turn-on Rise Time		--	35	--	nS
t _{d(off)}	Turn-Off Delay Time		--	30	--	nS
t _f	Turn-Off Fall Time		--	10	--	nS
Source- Drain Diode Characteristics						
V _{SD}	Forward on voltage	T _J =25°C, I _S =-11A,	--	--	-1.2	V

Typical Operating Characteristics


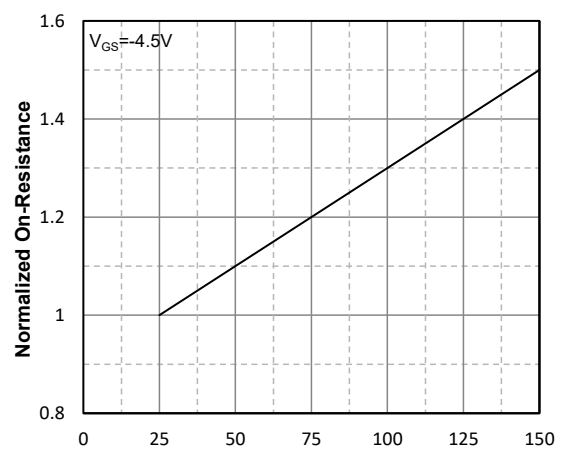
V_{DS} , Drain -Source Voltage (V)
Fig1. Typical Output Characteristics



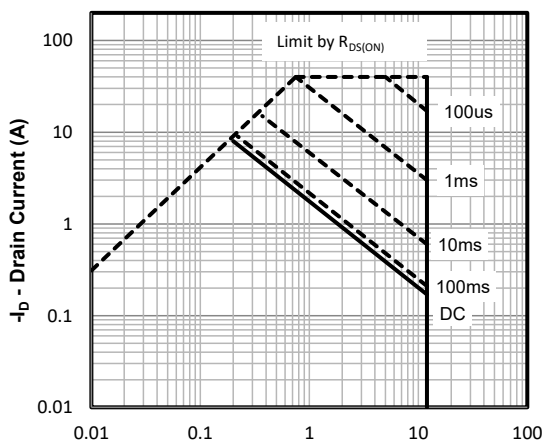
Q_g -Total Gate Charge (nC)
Fig2. Typical Gate Charge Vs. Gate-Source Voltage



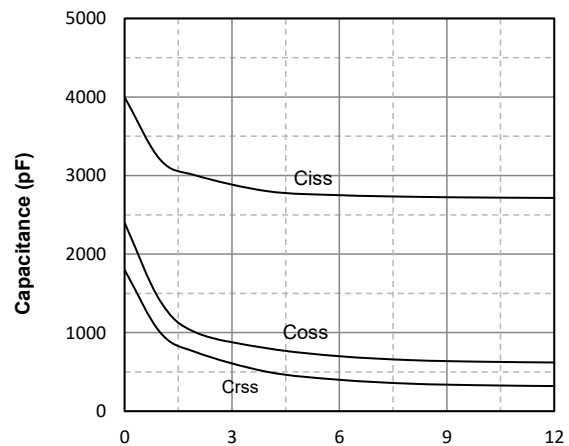
I_D , Drain-Source Current (mA)
Fig3. Drain-Source on Resistance



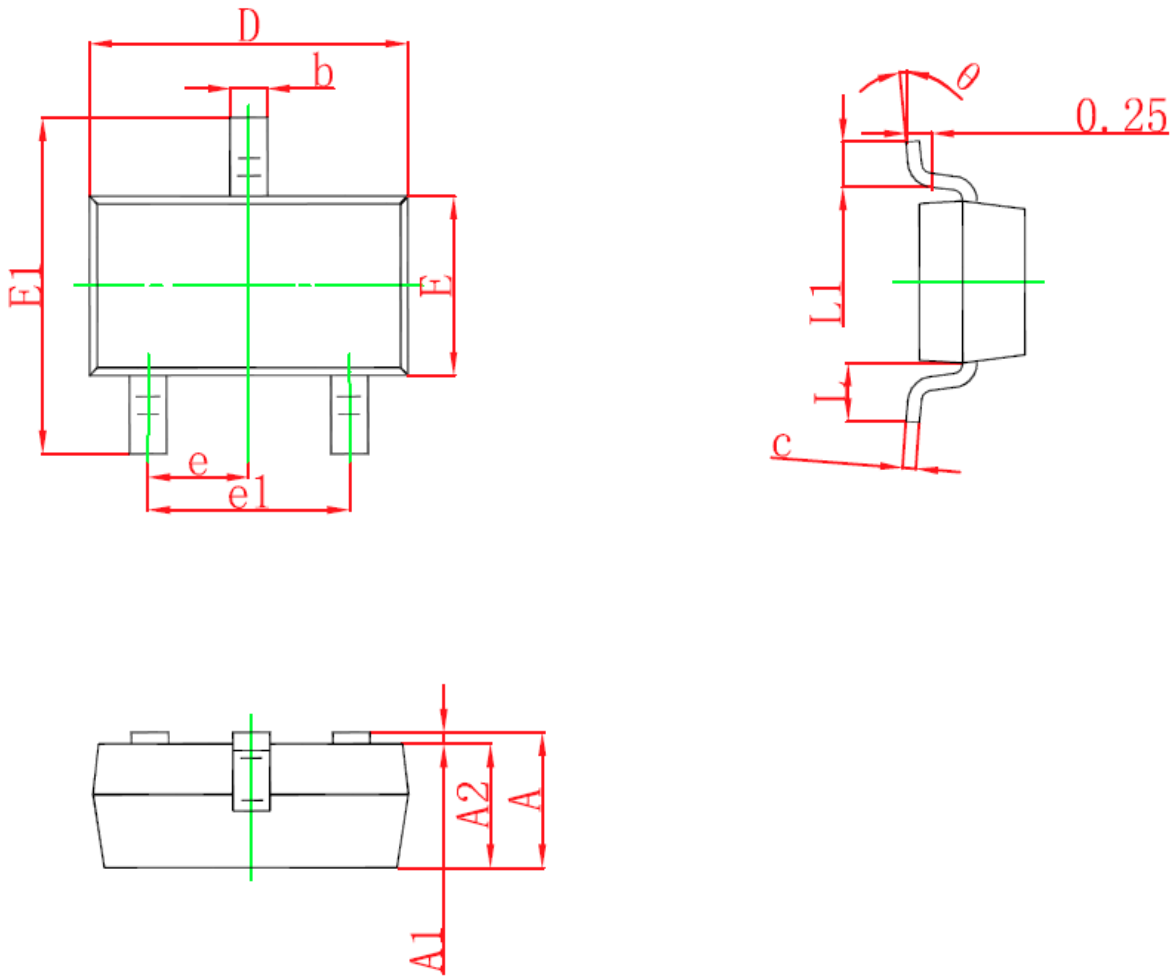
T_j - Junction Temperature ($^{\circ}C$)
Fig4. Normalized On-Resistance Vs. Temperature



V_{DS} , Drain -Source Voltage (V)
Fig5. Maximum Safe Operating Area



V_{DS} , Drain-Source Voltage (V)
Fig6 Typical Capacitance Vs. Drain-Source Voltage

SOT-23 Package information


Symbol	Dimensions in Millimeters(mm)		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E1	2.250	2.550	0.088	0.100
E	1.200	1.400	0.047	0.055
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°